

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

RELEASE BY SECURED PARTY

CONVEYING PARTY DATA

Name	Execution Date
Enterprise Partners VI, L.P., as collateral agent	06/10/2011
Enterprise Partners VI, L.P.	06/10/2011
Enterprise Partners V, L.P.	06/10/2011
Richard S. Post	06/10/2011

RECEIVING PARTY DATA

Name:	Nexx Systems, Inc., a Delaware Corporation
Street Address:	900 Middlesex Turnpike
Internal Address:	Building 6
City:	Billerica
State/Country:	MASSACHUSETTS
Postal Code:	01821

PROPERTY NUMBERS Total: 6

Property Type	Number
Patent Number:	6217272
Patent Number:	6328858
Patent Number:	6396024
Patent Number:	6530733
Patent Number:	6682288
Patent Number:	6821912

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

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PATENT
REEL: 027184 FRAME: 0423

CH \$240.00 6217272

Correspondent Name: Kristen I. Spano
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Address Line 4: Detroit, MICHIGAN 48226

ATTORNEY DOCKET NUMBER:	125055-810
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NAME OF SUBMITTER:	Kristen I. Spano
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Total Attachments: 3
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REASSIGNMENT AND RELEASE OF SECURITY INTEREST

This Reassignment and Release of Security Interest is made as of June 10, 2011 by the following (collectively as "Secured Party"):

Enterprise Partners VI, L.P., as collateral agent
Enterprise Partners VI, L.P.,
Enterprise Partners V, L.P.,
Richard S. Post.

in favor of **Nexx Systems, Inc.**, a Delaware corporation ("Grantor"), with its principal place of business at 900 Middlesex Turnpike, Building 6, Billerica, Massachusetts 01821.

Grantor has collaterally assigned certain interests in the patents described on Exhibit A ("Patents") to Secured Party under the Loan and Security Agreement dated as of October 31, 2007, and recorded with the United States Patent and Trademark Office as set forth on Exhibit A.

Secured Party hereby releases its security interest in the Patents and reassigns to Grantor, without warranty or recourse, all interest of Secured Party in the Patents.

Enterprise Partners VI, L.P., as collateral agent

By: Carl Eibl
Name: CARL EIBL
Its: MANAGING PARTNER

Enterprise Partners VI, L.P.

By: Carl Eibl
Name: CARL EIBL
Its: MANAGING PARTNER

Enterprise Partners V, L.P.

By: Carl Eibl
Name: CARL EIBL
Its: MANAGING PARTNER

Signature: _____

Name: **Richard S. Post**

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Enterprise Partners VI, L.P., as collateral agent

By: _____
Name: _____
Its: _____

Enterprise Partners VI, L.P.

By: _____
Name: _____
Its: _____

Enterprise Partners V, L.P.

By: _____
Name: _____
Its: _____

Signature: 
Name: **Richard S. Post**

EXHIBIT A
Patents

<u>Patent / Application Number</u>	<u>Recordation Date</u>	<u>Reel/Frame Number</u>	<u>Description</u>
6,217,272	11/04/04 11/05/04	015328/0752 015334/0079	In-Line sputter deposition system
6,251,250	11/05/04	015334/0071	Method of and apparatus for controlling fluid flow and electric fields involved in the electroplating of substantially flat workpieces and the like and more generally controlling fluid flow in the processing of other workpiece surfaces as well
6,328,858	11/04/04 11/05/04	015328/0752 015334/0079	Multi-layer sputter deposition apparatus
6,396,024	11/04/04 11/05/04	015328/0752 015334/0079	Permanent magnet ECR plasma source with integrated multipolar magnetic confinement
6,530,733	11/04/04 11/05/04	015328/0752 015334/0079	Substrate processing pallet and related substrate processing method and machine
6,682,288	11/04/04 11/05/04	015328/0752 015334/0079	Substrate processing pallet and related substrate processing method and machine
6,821,912	11/04/04 11/05/04	015328/0752 015334/0079	Substrate processing pallet and related substrate processing method and machine
7,100,954	11/04/04	015328/0752	Ultra-thin wafer handling system